

Listing of Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Claim 1 (currently amended):

A thermal dissipating element of a chip, comprising:

a cover including a top plate and a side plate, said top plate curving and extendedly connecting to be said side plate, wherein said top plate has a top surface and a bottom surface ; and

a lump including a top face, a bottom face and a side, wherein said lump is fastened inside said cover, and said top face contacts with said bottom surface.

Claim 2 (original) :

The thermal dissipating element according to claim 1, wherein said bottom face contacts with said chip.

Claim 3 (original) :

The thermal dissipating element according to claim 1, wherein the shape of said bottom face is circular.

Claim 4 (original) :

The thermal dissipating element according to claim 1, wherein the shape of said bottom face is quadrilateral.

Claim 5 (original) :

The thermal dissipating element according to claim 1, wherein said top

face is fastened on said bottom surface by an adhesive.

Claim 6 (original) :

The thermal dissipating element according to claim 1, wherein the shape of said top face is circular.

Claim 7 (original) :

The thermal dissipating element according to claim 1, wherein the shape of said top face is quadrilateral.

Claim 8 (original) :

The thermal dissipating element according to claim 1, wherein said side contacts with said side plate.

Claim 9 (original) :

The thermal dissipating element according to claim 1, wherein said lump is a silicon chip.

Claim 10 (original) :

The thermal dissipating element according to claim 1, further comprising a sole plate to extendedly connect to said side plate.

Claim 11 (original) :

The thermal dissipating element according to claim 10, said side plate and said sole plate including a plurality of holes, said holes being formed between said side plate and said sole plate.

Claim 12 (original) :

12. The thermal dissipating element according to claim 10, wherein said

sole plate includes a plurality of cavities.

Claim 13 (original) :

The thermal dissipating element according to claim 1, wherein the material of said lump is metal.

Claim 14 (original) :

The thermal dissipating element according to claim 13, wherein the material of said lump is aluminum.

Claim 15 (original) :

The thermal dissipating element according to claim 13, wherein the material of said lump is copper.

Claim 16 (currently amended) :

A chip packaging element, comprising :

- a substrate ;

- a chip fastened on said substrate ; and

- a thermal dissipating element of said chip, said thermal dissipating element including a top plate, a side plate, a sole plate and a lump, said top plate curving and extendedly connecting to the side plate, said side plate curving and extendedly connecting to the sole plate, said lump fastened on said top plate, wherein said sole plate is fastened on said substrate, said lump contacts with said chip, and said chip is fastened on said lump and said substrate.

Claim 17 (original) :

The chip packaging element according to claim 16, wherein said lump is fastened on said top plate by an adhesive with high thermal conductivity.

Claim 18 (original) :

The chip packaging element according to claim 16, wherein said lump contacts with a portion of said side plate.

Claim 19 (original) :

The chip packaging element according to claim 16, said lump comprising a top surface and a bottom surface being opposite to each other, wherein said lump is fastened on a portion of said bottom surface.

Claim 20 (original) :

The chip packaging element according to claim 16, said lump comprising a top surface and a bottom surface being opposite to each other, wherein said lump is fastened on all of said bottom surface.